

Accepted Manuscript

Atmospherically sintered copper-base alloy application film with self-assembled barrier layer on silicon substrate for silicon photovoltaics

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PII: S0925-8388(18)31771-7

DOI: [10.1016/j.jallcom.2018.05.086](https://doi.org/10.1016/j.jallcom.2018.05.086)

Reference: JALCOM 46059

To appear in: *Journal of Alloys and Compounds*

Received Date: 12 January 2018

Revised Date: 10 April 2018

Accepted Date: 7 May 2018

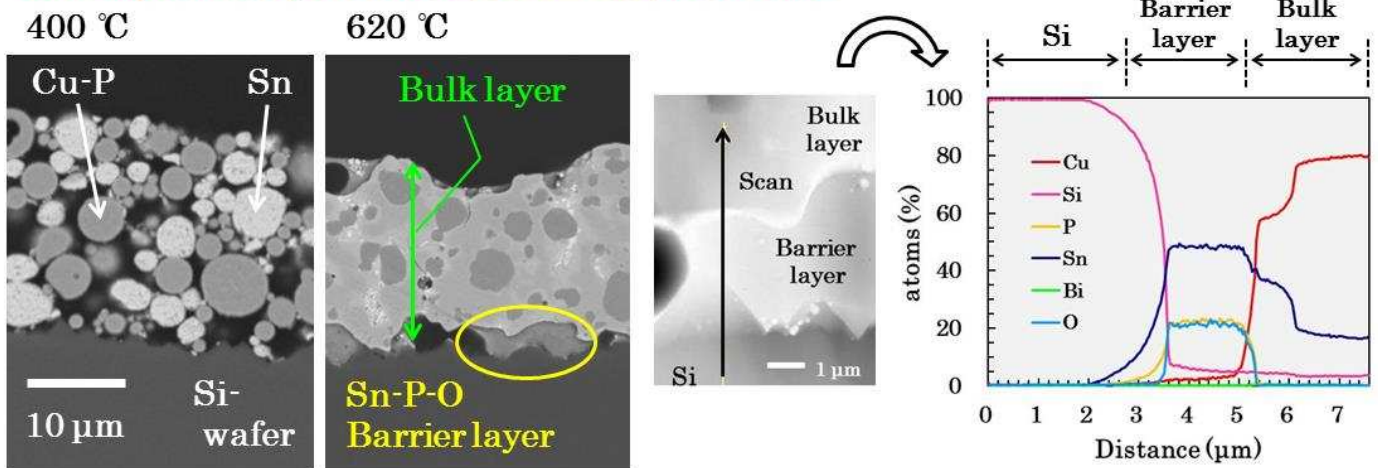
Please cite this article as: S. Adachi, T. Nojiri, T. Kato, S. Watanabe, M. Yoshida, Atmospherically sintered copper-base alloy application film with self-assembled barrier layer on silicon substrate for silicon photovoltaics, *Journal of Alloys and Compounds* (2018), doi: 10.1016/j.jallcom.2018.05.086.

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Graphical abstract

Atmospherically sintered Cu-P + Sn electrode



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